

IN THE SPECIFICATION:

Please insert the following new paragraph after the Title and before the "TECHNICAL FIELD":

-- RELATED APPLICATIONS

This application is the U.S. National Phase under 35 U.S.C. § 371 of International Application No. PCT/JP2005/009269, filed on May 20, 2005, which in turn claims the benefit of Japanese Application No. 2004-182692, filed on June 21, 2004, the disclosures of which Applications are incorporated by reference herein. --

Please amend the paragraph beginning on page 17 at line 2 as follows:

FIGS. **3(a)** through 3(c) ~~and 3(b)~~ are cross-sectional views of relevant part of a semiconductor device according to the first embodiment of the present invention illustrating respective steps for fabricating the semiconductor device.